

ABSTRACT

A bottom heat dissipating device may be attached to a bottom surface of a printed circuit board (PCB). A top surface of the bottom heat dissipating device may be thermally coupled with a backside surface of one or more electronic components mounted on the bottom surface of the PCB. A top heat dissipating device may be attached to a top surface of the PCB. The top heat dissipating device may be thermally coupled with the bottom heat dissipating device through a thermally conductive coupling member to provide a conductive path for heat transfer from the bottom heat dissipating device to the top heat dissipating device. An opening adjacent to an edge of the thermally conductive coupling member may allow air flow between the top and bottom heat dissipating devices. The PCB may be part of a mezzanine card, such as a Peripheral Component Interconnect (PCI) mezzanine card (PMC).